



Material Content Data Sheet



Sales Product Name	IDH12S60C			Issued		7. December 2015		
MA#	MA000800256							
Package	PG-TO220-2-1			Weight*		1972.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.339	0.17	0.17	1693	1693
leadframe	non noble metal	iron	7439-89-6	0.753	0.04		382	
	inorganic material	phosphorus	7723-14-0	0.226	0.01		115	
	non noble metal	copper	7440-50-8	751.797	38.11	38.16	381194	381692
wire	non noble metal	aluminium	7429-90-5	2.628	0.13	0.13	1332	1332
encapsulation	organic material	carbon black	1333-86-4	9.028	0.46		4577	
	plastics	epoxy resin	-	99.303	5.04		50351	
	inorganic material	silicondioxide	60676-86-0	493.504	25.02	30.52	250230	305158
leadfinish	non noble metal	tin	7440-31-5	14.668	0.74	0.74	7437	7437
plating	non noble metal	nickel	7440-02-0	0.198	0.01		100	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	1	100
solder	noble metal	silver	7440-22-4	0.163	0.01		83	
	non noble metal	tin	7440-31-5	0.131	0.01		66	
	non noble metal	lead	7439-92-1	6.239	0.32	0.34	3163	3312
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		299	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		90	
	non noble metal	copper	7440-50-8	589.466	29.89	29.93	298887	299276
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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